

Product Specification

Product:	Dielectric Paste
Part Number:	07H-1805

Application Scope :

This paste is suitable for outer-layer encapsulation of thick-film circuits.

Usage Conditions :

Substrate	Thick-film circuit, alumina ceramic
Usage Method	Printing, 200-250 mesh
Leveling	Let it level at room temperature for 5-10 minutes (adjust time based on actual leveling conditions).
Drying	Bake in a ventilation oven at 100-150°C for 10-15 minutes (if the baking temperature is below 300°C, the baking time may be adjusted based on actual conditions).
Firing Condition	The sintering temperature is 850°C (recommended value) and the sintering time is 10 minutes.
Thinner	ST-1001

Characteristics :

1. Paste Characteristics :

Characteristic	Standard	Test Method And Conditions
1 Fineness	≤8μm	FOG test
2 Viscosity	100~200Pa.s	Brookfield HBT (Boli Fei) viscometer, rotor SC4-14/6R, 10 rpm, 25±1°C
3 Appearance	Transparent, Black, Blue, Green	

2. Characteristics After Curing :

Under the condition of 1 sintering, Check fired film produced under the conditions specified in 1)

Characteristics	Standard	Test Method And Conditions
4 Appearance	Compact and dense	Visual inspection & microscopy



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Save Conditions And Validity Period :

The product shall be stored in a sealed container at an ambient temperature of 5-15°C, with a shelf life of 1 year from the date of shipment.

Packaging Method :

Standard packaging, 1000g/can; samples are available in 200g small can packaging.